



## Material Content Data Sheet



<b>Sales Product Name</b>				IAUC70N08S5N074		<b>Issued</b>		9. January 2019	
<b>MA#</b>				MA002050954					
<b>Package</b>				PG-TDSON-8-33		<b>Weight*</b>		111.70 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.635	0.57	0.57	5686	5686	
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		142		
	non noble metal	iron	7439-89-6	0.053	0.05		474		
	non noble metal	copper	7440-50-8	52.842	47.30	47.36	473067	473683	
	noble metal	gold	7440-57-5	0.043	0.04	0.04	388	388	
wire	noble metal	gold	7440-57-5	0.043	0.04	0.04	388	388	
encapsulation	organic material	carbon black	1333-86-4	0.076	0.07		684		
	plastics	epoxy resin	-	6.039	5.41		54068		
	inorganic material	silicondioxide	60676-86-0	32.108	28.74	34.22	287449	342201	
leadfinish	non noble metal	tin	7440-31-5	1.574	1.41	1.41	14089	14089	
plating	noble metal	silver	7440-22-4	0.209	0.19	0.19	1873	1873	
solder	non noble metal	tin	7440-31-5	0.019	0.02		169		
	noble metal	silver	7440-22-4	0.024	0.02		212		
	non noble metal	lead	7439-92-1	0.902	0.81	0.85	8079	8460	
heatspreader	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	iron	7439-89-6	0.000	0.00		3		
	non noble metal	copper	7440-50-8	0.310	0.28	0.28	2771	2775	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.00		45		
	non noble metal	iron	7439-89-6	0.017	0.02		151		
	non noble metal	copper	7440-50-8	16.828	15.06	15.08	150649	150845	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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